Amendments to the Claims

This listing of the claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1-24. (cancelled)

25. (currently amended) A processing method for a fuse structure, the method comprising ~~the steps of~~:

providing a structure;

forming a first conductive layer and a second conductive layer on part of the structure;

forming a first dielectric layer on the first conductive layer, the second conductive layer and the structure;

forming a first opening on the first dielectric layer, exposing the first conductive layer and the second conductive layer;

~~implanting~~ forming a first conductive plug in the first opening to contact ~~to penetrate~~ the first conductive layer ~~via the first opening~~;

forming a third conductive layer and a fourth conductive layer on part of the first dielectric layer;

forming a second dielectric layer on the third conductive layer, the fourth conductive layer and the first dielectric layer;

forming a second opening on the second dielectric layer, exposing the first opening, the third conductive layer and the fourth conductive layer;

~~implanting~~ forming ~~the~~ a second conductive plug in the second opening to contact the third conductive layer ~~to penetrate the second dielectric layer via the second opening~~;

forming a fifth conductive layer, a sixth conductive layer, a seventh conductive layer, an eighth conductive layer, a ninth conductive layer and a tenth conductive layer on part of the second dielectric layer, wherein a third conductive plug is electrically connected to the fourth conductive layer

and the fifth conductive layer, a fourth conductive plug is electrically connected to the second conductive layer and the sixth conductive layer, the third conductive layer is electrically connected to the ninth conductive layer and the eighth conductive layer is electrically connected to the first conductive layer.

26. (currently amended) A processing method for a fuse structure, the method comprising ~~the steps of~~:

forming a substrate;

forming a ~~eleventh~~first conductive layer, a ~~twelfth~~second conductive layer, a ~~thirteenth~~third conductive layer and a ~~fourteenth~~fourth conductive layer on part of the substrate;

forming a first dielectric layer on the ~~eleventh~~first conductive layer, the ~~twelfth~~second conductive layer, the ~~thirteenth~~third conductive layer, the ~~fourteenth~~fourth conductive layer and the substrate;

forming a ~~fifteenth~~fifth conductive layer, a ~~sixteenth~~sixth conductive layer, a ~~seventeenth~~seventh conductive layer, an ~~eighteenth~~eighth conductive layer on part of the first dielectric layer;

forming a second dielectric layer on the ~~fifteenth~~fifth conductive layer, the ~~sixteenth~~sixth conductive layer, the ~~seventeenth~~seventh conductive layer, the ~~eighteenth~~eighth conductive layer and the first dielectric layer;

forming an opening on the first dielectric layer and second dielectric layer, exposing the ~~eleventh~~first conductive layer, the ~~twelfth~~second conductive layer, the ~~thirteenth~~third conductive layer, ~~fourteenth~~fourth conductive layer, ~~fifteenth~~fifth conductive layer, the ~~sixteenth~~sixth conductive layer, the ~~seventeenth~~seventh conductive layer and the ~~eighteenth~~eighth conductive layer;

~~implanting~~forming a conductive plug in the opening, to penetrate the first dielectric layer and the second dielectric layer; and

forming a ~~nineteenth~~ninth conductive layer, a ~~twentieth~~tenth conductive layer, an ~~twenty-first~~eleventh conductive layer, ~~twenty-second~~twelfth conductive layer, a ~~twenty-third~~thirteenth conductive layer, a ~~twenty-fourth~~fourteenth conductive layer, a ~~twenty-fifth~~fifteenth conductive layer, a ~~twenty-sixth~~sixteenth conductive layer, a ~~twenty-seventh~~seventeenth conductive layer and an ~~twenty-eighth~~eighteenth conductive layer on part of the second dielectric layer, wherein a ~~eleventh~~first conductive plug is electrically connected to the ~~fifteenth~~fifth conductive layer and ~~nineteenth~~ninth conductive layer, a ~~twelfth~~second conductive plug is electrically connected to the ~~eleventh~~first conductive layer and the ~~twentieth~~tenth conductive layer, a ~~thirteenth~~third conductive plug is electrically connected to the ~~twenty-sixth~~sixteenth conductive layer and the ~~twelfth~~second conductive layer, a ~~fourteenth~~fourth conductive plug is electrically connected to the ~~twenty-seventh~~seventeenth conductive layer and the ~~sixteenth~~sixth conductive layer, a ~~fifteenth~~fifth conductive plug is electrically connected to the ~~twenty-first~~eleventh conductive layer and the ~~thirteenth~~third conductive layer, a ~~sixteenth~~sixth conductive plug is electrically connected to the ~~twenty-second~~twelfth conductive layer and the ~~seventeenth~~seventh conductive layer, a ~~seventeenth~~seventh conductive plug is electrically connected to the ~~twenty-fourth~~fourteenth conductive layer and ~~eighteenth~~eighth conductive layer, and an ~~eighteenth~~eighth conductive plug is electrically connected to the ~~twenty-fifth~~fifteenth conductive layer and the ~~fourteenth~~fourth conductive layer.

27. (new) A processing method for a fuse structure, the method comprising:

providing a substrate;

forming a first conductor, a second conductor and a first dielectric layer on the substrate, wherein the first conductor and the second conductor are disposed between the substrate and the first dielectric layer;

forming a third conductor, a fourth conductor and a second dielectric layer on the first dielectric layer, wherein the third conductor and the fourth conductor are disposed between the second dielectric layer and the first dielectric layer;

forming a plurality of openings to expose the first conductor, the second conductor, the third conductor and the fourth conductor;

forming a conductive plug within each opening of the plurality of openings;

forming a fifth conductor on the second dielectric layer to be in electrical contact with the fourth conductor through the conductive plug within one of the opening of the plurality of openings;

forming a sixth conductor on the second dielectric layer to be in electrical contact with the second conductor through the conductive plug within one of the opening of the plurality of openings;

forming a seventh conductor on the second dielectric layer;

forming an eighth conductor on the second dielectric layer to be in electrical contact with the first conductor through the conductive plug within one of the opening of the plurality of openings;

forming a ninth conductor on the second dielectric layer to be in electrical contact with the third conductor through the conductive plug within one of the opening of the plurality of openings; and

forming a tenth conductor on the second dielectric layer.

28. (new) A processing method for a fuse structure, the method comprising:

providing a substrate;

forming a first conductor, a second conductor, a third conductor, a fourth conductor and a first dielectric layer on the substrate, wherein the first conductor, the second conductor, the third conductor and the fourth conductor are disposed between the substrate and the first dielectric layer;

forming a fifth conductor, a sixth conductor, a seventh conductor, an eighth conductor and a second dielectric layer on the first dielectric layer, wherein the fifth conductor, the sixth conductor, the seventh conductor and the eighth

conductor are disposed between the second dielectric layer and the first dielectric layer;

forming a plurality of openings to expose the first conductor, the second conductor, the third conductor, the fourth conductor, the fifth conductor, the sixth conductor, the seventh conductor and the eighth conductor;

forming a conductive plug within each opening of the plurality of openings;

forming a ninth conductor on the second dielectric layer to be in electrical contact with the fifth conductor through the conductive plug within one of the opening of the plurality of openings;

forming a tenth conductor on the second dielectric layer to be in electrical contact with the first conductor through the conductive plug within one of the opening of the plurality of openings;

forming an eleventh conductor on the second dielectric layer to be in electrical contact with the third conductor through the conductive plug within one of the opening of the plurality of openings;

forming a twelfth conductor on the second dielectric layer to be in electrical contact with the seventh conductor through the conductive plug within one of the opening of the plurality of openings;

forming a thirteenth conductor on the second dielectric layer;

forming a fourteenth conductor on the second dielectric layer to be in electrical contact with the eighth conductor through the conductive plug within one of the opening of the plurality of openings;

forming a fifteenth conductor on the second dielectric layer to be in electrical contact with the fourth conductor through the conductive plug within one of the opening of the plurality of openings;

forming a sixteenth conductor on the second dielectric layer to be in electrical contact with the second conductor through the conductive plug within one of the opening of the plurality of openings;

forming a seventeenth conductor on the second dielectric layer to be in electrical contact with the sixth conductor through the conductive plug within one of the opening of the plurality of openings; and

forming an eighteenth conductor on the second dielectric layer.